Chip Beads HF30ACC321611-T

| Applications | Com | nmercial Grade |
|--------------|-----------------------------------|----------------|
| Feature | Signal Sign | al Line |
| Series | HFxxACC Series / HFxxACC3216 Type | |
| Status | Production | |
| | | |



| Size | | | |
|------------------------------|------------------|--|--|
| Length(L) | 3.20mm +/-0.20mm | | |
| Width(W) | 1.60mm +/-0.20mm | | |
| Thickness(T) | 1.10mm +/-0.20mm | | |
| Recommended Land Pattern (A) | 1.10mm Nom. | | |
| Recommended Land Pattern (B) | 2.20mm Nom. | | |
| Recommended Land Pattern (C) | 1.40mm Nom. | | |

| Electrical Characteristics | | | |
|----------------------------|------------|--|--|
| Impedance at 100MHz | 19Ω +/-25% | | |
| Rated Current | 1.5A | | |
| DC Resistance [Max.] | 40mΩ | | |

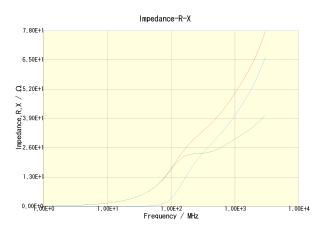
| Other | | | | |
|---|--------------------------------------|--|--|--|
| Operating Temp. Range (Including Self-Temp. Rise) | -40 to 125degC | | | |
| Soldering Method | Reflow, Iron Soldering | | | |
| AEC Q200 | No | | | |
| Packing | Blister (Plastic)Taping [180mm Reel] | | | |
| Package Quantity | 2000Pcs Min. | | | |
| Weight | 0.022g | | | |

•This PDF document was created based on the data listed on the TDK Corporation website.

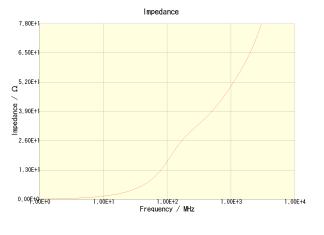
•All specifications are subject to change without notice.

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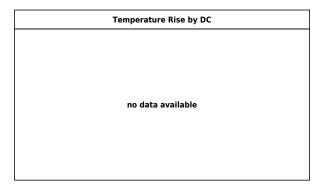
Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)



HF30ACC321611-T(|Z|) HF30ACC321611-T(R) HF30ACC321611-T(X)



HF30ACC321611-T



| Derating |
|-------------------|
| |
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| |
| no data available |
| |
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